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Attorney's Docket No. 042390.P5832

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application for:

Donald S. Gardner, et al.

Serial No. 09/253,306

Filed: February 19, 1999

For: *Interconnection Alloy for  
Integrated Circuits*

Examiner: Tran, T.

Art Unit: 2811

2/23/00  
J. Smith

AMENDMENT AND RESPONSE TO OFFICE ACTION

Box Non-Fee Amendments  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

In response to the Office Action mailed October 25, <sup>1999</sup>~~2000~~,

Applicants respectfully request entry of the following amendments.

IN THE CLAIMS

Please cancel claims 1-3, 7, 8, 12, 13, 17 and 18

Please amend the claims as follows:

- Sub  
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- 1 4. (Amended) [The interconnection of claim 2,] An
  - 2 interconnection comprising:
  - 3 an aluminum copper titanium alloy layer, wherein the
  - 4 aluminum-copper-titanium alloy layer contains about 0.1 atomic
  - 5 percent titanium.